### NXP USA Inc. - MC9S08SH16CTG Datasheet





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#### Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	13
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08sh16ctg

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# **Revision History**

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

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The following revision history table summarizes changes contained in this document.

Revision Number	Revision Date	Description of Changes
1	10/2007	Updated The ACMP and TPM modules to version 3 and made numerous revisions to the Electricals. Updated device numbering scheme.
2	4/2008	Updated some electricals and made some minor grammatical/formatting revi- sions. Corrected the SPI block module version. Removed incorrect ADC temper- ature sensor value from the Features section. Updated the package information with a sample mask set identifier.
3	3/2014	Added a note to the Section 9.1, "Introduction"; updated Section 11.4.5, "Internal Reference Clock"; updated Section A.14.1, "Radiated Emissions"; updated Figure 4-1, Figure 4-6; updated Table 4-4; updated Table 7-2.

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## 4.5.1 Features

Features of the FLASH memory include:

- FLASH size
  - MC9S08SH32: 32,768 bytes (64 pages of 512 bytes each)
  - MC9S08SH16: 16,384 bytes (32 pages of 512 bytes each)
- Single power supply program and erase
- Command interface for fast program and erase operation
- Up to 100,000 program/erase cycles at typical voltage and temperature
- Flexible block protection and vector redirection
- Security feature for FLASH and RAM
- Auto power-down for low-frequency read accesses

## 4.5.2 Program and Erase Times

Before any program or erase command can be accepted, the FLASH clock divider register (FCDIV) must be written to set the internal clock for the FLASH module to a frequency ( $f_{FCLK}$ ) between 150 kHz and 200 kHz (see Section 4.7.1, "FLASH Clock Divider Register (FCDIV)"). This register can be written only once, so normally this write is done during reset initialization. FCDIV cannot be written if the access error flag, FACCERR in FSTAT, is set. The user must ensure that FACCERR is not set before writing to the FCDIV register. One period of the resulting clock ( $1/f_{FCLK}$ ) is used by the command processor to time program and erase pulses. An integer number of these timing pulses are used by the command processor to complete a program or erase command.

Table 4-5 shows program and erase times. The bus clock frequency and FCDIV determine the frequency of FCLK ( $f_{FCLK}$ ). The time for one cycle of FCLK is  $t_{FCLK} = 1/f_{FCLK}$ . The times are shown as a number of cycles of FCLK and as an absolute time for the case where  $t_{FCLK} = 5 \ \mu$ s. Program and erase times shown include overhead for the command state machine and enabling and disabling of program and erase voltages.

Parameter	Cycles of FCLK	Time if FCLK = 200 kHz
Byte program	9	45 μs
Byte program (burst)	4	20 μs <sup>1</sup>
Page erase	4000	20 ms
Mass erase	20,000	100 ms

#### Table 4-5. Program and Erase Times

<sup>1</sup> Excluding start/end overhead

Table 4-12	. FSTAT	Register	Field	Descriptions	(continued)
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Field	Description
4 FACCERR	<ul> <li>Access Error Flag — FACCERR is set automatically when the proper command sequence is not obeyed exactly (the erroneous command is ignored), if a program or erase operation is attempted before the FCDIV register has been initialized, or if the MCU enters stop while a command was in progress. For a more detailed discussion of the exact actions that are considered access errors, see Section 4.5.5, "Access Errors." FACCERR is cleared by writing a 1 to FACCERR. Writing a 0 to FACCERR has no meaning or effect.</li> <li>0 No access error.</li> <li>1 An access error has occurred.</li> </ul>
2 FBLANK	<ul> <li>FLASH Verified as All Blank (erased) Flag — FBLANK is set automatically at the conclusion of a blank check command if the entire FLASH array was verified to be erased. FBLANK is cleared by clearing FCBEF to write a new valid command. Writing to FBLANK has no meaning or effect.</li> <li>O After a blank check command is completed and FCCF = 1, FBLANK = 0 indicates the FLASH array is not completely erased.</li> <li>1 After a blank check command is completed and FCCF = 1, FBLANK = 1 indicates the FLASH array is completely erased (all 0xFF).</li> </ul>

# 4.7.6 FLASH Command Register (FCMD)

Only five command codes are recognized in normal user modes as shown in Table 4-13. Refer to Section 4.5.3, "Program and Erase Command Execution," for a detailed discussion of FLASH programming and erase operations.



Figure 4-10. FLASH Command Register (FCMD)

Command	FCMD	Equate File Label
Blank check	0x05	mBlank
Byte program	0x20	mByteProg
Byte program — burst mode	0x25	mBurstProg
Page erase (512 bytes/page)	0x40	mPageErase
Mass erase (all FLASH)	0x41	mMassErase

Table 4-13. FLASH Commands

All other command codes are illegal and generate an access error.

It is not necessary to perform a blank check command after a mass erase operation. Only blank check is required as part of the security unlocking mechanism.



#### Chapter 5 Resets, Interrupts, and General System Control

When an interrupt condition occurs, an associated flag bit becomes set. If the associated local interrupt enable is 1, an interrupt request is sent to the CPU. Within the CPU, if the global interrupt mask (I bit in the CCR) is 0, the CPU will finish the current instruction; stack the PCL, PCH, X, A, and CCR CPU registers; set the I bit; and then fetch the interrupt vector for the highest priority pending interrupt. Processing then continues in the interrupt service routine.

Vector Priority	Vector Number	Address (High/Low)	Vector Name	Module	Source	Enable	Description
	31	0xFFC0/0xFFC1	—		_		—
Lowest	30	0xFFC2/0xFFC3	Vacmp	ACMP	ACF	ACIE	Analog comparator
Lowoot	29	0xFFC4/0xFFC5	—		_	_	—
	28	0xFFC6/0xFFC7	—		_	_	—
	27	0xFFC8/0xFFC9	—		_	_	—
	26	0xFFCA/0xFFCB	Vmtim	MTIM	TOF	TOIE	MTIM overflow
	25	0xFFCC/0xFFCD	Vrtc	RTC	RTIF	RTIE	Real-time interrupt
	24	0xFFCE/0xFFCF	Viic	IIC	IICIS	IICIE	IIC control
	23	0xFFD0/0xFFD1	Vadc	ADC	COCO	AIEN	ADC
	22	0xFFD2/0xFFD3	—		_	_	_
	21	0xFFD4/0xFFD5	Vportb	Port B	PTBIF	PTBIE	Port B Pins
	20	0xFFD6/0xFFD7	Vporta	Port A	PTAIF	PTAIE	Port A Pins
	19	0xFFD8/0xFFD9	—		_	_	_
	18	0xFFDA/0xFFDB	Vscitx	SCI	TDRE, TC	TIE, TCIE	SCI transmit
	17	0xFFDC/0xFFDD	Vscirx	SCI	IDLE, RDRF, LDBKDIF, RXEDGIF	ILIE, RIE, LBKDIE, RXEDGIE	SCI receive
	16	0xFFDE/0xFFDF	Vscierr	SCI	OR, NF, FE, PF	ORIE, NFIE, FEIE, PFIE	SCI error
	15	0xFFE0/0xFFE1	Vspi	SPI	SPIF, MODF, SPTEF	SPIE, SPIE, SPTIE	SPI
	14	0xFFE2/0xFFE3	Vtpm2ovf	TPM2	TOF	TOIE	TPM2 overflow
	13	0xFFE4/0xFFE5	Vtpm2ch1	TPM2	CH1F	CH1IE	TPM2 channel 1
	12	0xFFE6/0xFFE7	Vtpm2ch0	TPM2	CH0F	CH0IE	TPM2 channel 0
	11	0xFFE8/0xFFE9	Vtpm1ovf	TPM1	TOF	TOIE	TPM1 overflow
	10	0xFFEA/0xFFEB	—	_		_	—
	9	0xFFEC/0xFFED			_	_	—
	8	0xFFEE/0xFFEF	—	_	—	—	—
	7	0xFFF0/0xFFF1	—	_	—	—	—
	6	0xFFF2/0xFFF3	Vtpm1ch1	TPM1	CH1F	CH1IE	TPM1 channel 1
	5	0xFFF4/0xFFF5	Vtpm1ch0	TPM1	CH0F	CH0IE	TPM1 channel 0
	4	0xFFF6/0xFFF7	—	—		—	—
	3	0xFFF8/0xFFF9	Vlvd	System control	LVWF	LVWIE	Low-voltage warning
	2	0xFFFA/0xFFFB	Virq	IRQ	IRQF	IRQIE	IRQ pin
	1	0xFFFC/0xFFFD	Vswi	Core	SWI Instruction		Software interrupt
Highest	0	0xFFFE/0xFFFF	Vreset	System control	COP, LVD, RESET pin, Illegal opcode, Illegal address	COPE LVDRE — —	Watchdog timer Low-voltage detect External pin Illegal opcode Illegal address
		I					

#### Table 5-2. Vector Summary



Field	Description
3 ILAD	<ul> <li>Illegal Address — Reset was caused by an attempt to access either data or an instruction at an unimplemented memory address.</li> <li>Reset not caused by an illegal address</li> <li>Reset caused by an illegal address</li> </ul>
1 LVD	<ul> <li>Low Voltage Detect — If the LVDRE bit is set and the supply drops below the LVD trip voltage, an LVD reset will occur. This bit is also set by POR.</li> <li>0 Reset not caused by LVD trip or POR.</li> <li>1 Reset caused by LVD trip or POR.</li> </ul>

#### Table 5-4. SRS Register Field Descriptions

## 5.7.3 System Background Debug Force Reset Register (SBDFR)

This high page register contains a single write-only control bit. A serial background command such as WRITE\_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



<sup>1</sup> BDFR is writable only through serial background debug commands, not from user programs.

#### Figure 5-4. System Background Debug Force Reset Register (SBDFR)

#### Table 5-5. SBDFR Register Field Descriptions

Field	Description
0 BDFR	<b>Background Debug Force Reset</b> — A serial background command such as WRITE_BYTE can be used to allow an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.



# 5.7.8 System Power Management Status and Control 2 Register (SPMSC2)

This register is used to report the status of the low voltage warning function, and to configure the stop mode behavior of the MCU. This register should be written during the user's reset initialization program to set the desired controls even if the desired settings are the same as the reset settings.



<sup>1</sup> This bit can be written only one time after power-on reset. Additional writes are ignored.

<sup>2</sup> This bit can be written only one time after reset. Additional writes are ignored.

#### Figure 5-10. System Power Management Status and Control 2 Register (SPMSC2)

Field	Description
5 LVDV	<b>Low-Voltage Detect Voltage Select</b> — This write-once bit selects the low voltage detect (LVD) trip point setting. It also selects the warning voltage range. See Table 5-12.
4 LVWV	Low-Voltage Warning Voltage Select — This bit selects the low voltage warning (LVW) trip point voltage. See Table 5-12.
3 PPDF	<ul> <li>Partial Power Down Flag — This read-only status bit indicates that the MCU has recovered from stop2 mode.</li> <li>MCU has not recovered from stop2 mode.</li> <li>MCU recovered from stop2 mode.</li> </ul>
2 PPDACK	Partial Power Down Acknowledge — Writing a 1 to PPDACK clears the PPDF bit
0 PPDC	<ul> <li>Partial Power Down Control — This write-once bit controls whether stop2 or stop3 mode is selected.</li> <li>0 Stop3 mode enabled.</li> <li>1 Stop2, partial power down, mode enabled.</li> </ul>

#### Table 5-11. SPMSC2 Register Field Descriptions



#### Chapter 7 Central Processor Unit (S08CPUV3)

Source	Operation	dress lode	Object Code	/cles	Cyc-by-Cyc	Affect on CCR	
l i onn		PΦ Φ		ΰ	Details	<b>V</b> 1 1 <b>H</b>	INZC
BPL rel	Branch if Plus (if N = 0)	REL	2A rr	3	qqq	-11-	
BRA rel	Branch Always	REL	20 rr	3	qqq	- 1 1 -	
BRCLR n,opr8a,rel	Branch if Bit <i>n</i> in Memory Clear (if (Mn) = 0)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 dd rr 03 dd rr 05 dd rr 07 dd rr 09 dd rr 0B dd rr 0D dd rr 0F dd rr	5 5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp rpppp	- 1 1 -	\$
BRN rel	Branch Never	REL	21 rr	3	qqq	- 1 1 -	
BRSET n,opr8a,rel	Branch if Bit <i>n</i> in Memory Set (if (Mn) = 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 dd rr 02 dd rr 04 dd rr 06 dd rr 08 dd rr 0A dd rr 0C dd rr 0E dd rr	5 5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp	- 1 1 -	\$
BSET n,opr8a	Set Bit <i>n</i> in Memory (Mn ← 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 dd 12 dd 14 dd 16 dd 18 dd 1A dd 1C dd 1E dd	5 5 5 5 5 5 5 5 5 5 5	rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp	- 1 1 -	
BSR rel	$\begin{array}{c} \text{Branch to Subroutine} \\ \text{PC} \leftarrow (\text{PC}) + \$0002 \\ \text{push (PCL); SP} \leftarrow (\text{SP}) - \$0001 \\ \text{push (PCH); SP} \leftarrow (\text{SP}) - \$0001 \\ \text{PC} \leftarrow (\text{PC}) + \textit{rel} \end{array}$	REL	AD rr	5	qqqaa	- 1 1 -	
CBEQ opr8a,rel CBEQA #opr8i,rel CBEQX #opr8i,rel CBEQ oprx8,X+,rel CBEQ ,X+,rel CBEQ oprx8,SP,rel	Compare and Branch if $(A) = (M)$ Branch if $(A) = (M)$ Branch if $(X) = (M)$ Branch if $(A) = (M)$ Branch if $(A) = (M)$ Branch if $(A) = (M)$	DIR IMM IMM IX1+ IX+ SP1	31 dd rr 41 ii rr 51 ii rr 61 ff rr 71 rr 9E 61 ff rr	5 4 5 5 6	rpppp pppp pppp rpppp rfppp prpppp	- 1 1 -	
CLC	Clear Carry Bit (C $\leftarrow$ 0)	INH	98	1	q	- 1 1 -	0
CLI	Clear Interrupt Mask Bit (I $\leftarrow$ 0)	INH	9A	1	q	- 1 1 -	0
CLR opr8a CLRA CLRX CLRH CLR oprx8,X CLR ,X CLR oprx8,SP	Clear $M \leftarrow \$00$ $A \leftarrow \$00$ $X \leftarrow \$00$ $H \leftarrow \$00$ $M \leftarrow \$00$ $M \leftarrow \$00$ $M \leftarrow \$00$	DIR INH INH INH IX1 IX SP1	3F dd 4F 5F 8C 6F ff 7F 9E 6F ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	011-	- 0 1 -

Table 7-2. Instruction Set Summary (Sheet 3 of 9)







 $\triangle$  = Pin can be enabled as part of the ganged output drive feature

- NOTE: PTC7-PTC0 and PTA7-PTA6 not available on 16--pin Packages
  - PTC7-PTC4 and PTA7-PTA6 not available on 20-pin Packages
  - For the 16-pin and 20-pin packages: VDDA/VREFH and VSSA/VREFL, are double bonded to VDD and VSS respectively.
  - When PTA4 is configured as BKGD, pin becomes bi-directional.

Figure 8-1. MC9S08SH32 Series Block Diagram Highlighting ACMP Block and Pins



#### Chapter 9 Analog-to-Digital Converter (S08ADCV1)

- Average the result by converting the analog input many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ADACK) and averaging. Noise that is synchronous to ADCK cannot be averaged out.

## 9.6.2.4 Code Width and Quantization Error

The ADC quantizes the ideal straight-line transfer function into 1024 steps (in 10-bit mode). Each step ideally has the same height (1 code) and width. The width is defined as the delta between the transition points to one code and the next. The ideal code width for an N bit converter (in this case N can be 8 or 10), defined as 1LSB, is:

## $1LSB = (V_{REFH} - V_{REFL}) / 2^{N} \qquad Eqn. 9-2$

There is an inherent quantization error due to the digitization of the result. For 8-bit or 10-bit conversions the code will transition when the voltage is at the midpoint between the points where the straight line transfer function is exactly represented by the actual transfer function. Therefore, the quantization error will be  $\pm 1/2$ LSB in 8- or 10-bit mode. As a consequence, however, the code width of the first (\$000) conversion is only 1/2LSB and the code width of the last (\$FF or \$3FF) is 1.5LSB.

## 9.6.2.5 Linearity Errors

The ADC may also exhibit non-linearity of several forms. Every effort has been made to reduce these errors but the system should be aware of them because they affect overall accuracy. These errors are:

- Zero-scale error (E<sub>ZS</sub>) (sometimes called offset) This error is defined as the difference between the actual code width of the first conversion and the ideal code width (1/2LSB). Note, if the first conversion is \$001, then the difference between the actual \$001 code width and its ideal (1LSB) is used.
- Full-scale error  $(E_{FS})$  This error is defined as the difference between the actual code width of the last conversion and the ideal code width (1.5LSB). Note, if the last conversion is \$3FE, then the difference between the actual \$3FE code width and its ideal (1LSB) is used.
- Differential non-linearity (DNL) This error is defined as the worst-case difference between the actual code width and the ideal code width for all conversions.
- Integral non-linearity (INL) This error is defined as the highest-value the (absolute value of the) running sum of DNL achieves. More simply, this is the worst-case difference of the actual transition voltage to a given code and its corresponding ideal transition voltage, for all codes.
- Total unadjusted error (TUE) This error is defined as the difference between the actual transfer function and the ideal straight-line transfer function, and therefore includes all forms of error.

## 9.6.2.6 Code Jitter, Non-Monotonicity and Missing Codes

Analog-to-digital converters are susceptible to three special forms of error. These are code jitter, non-monotonicity, and missing codes.

Code jitter is when, at certain points, a given input voltage converts to one of two values when sampled repeatedly. Ideally, when the input voltage is infinitesimally smaller than the transition voltage, the



Chapter 11 Internal Clock Source (S08ICSV2)



Figure 11-2. Internal Clock Source (ICS) Block Diagram

## 11.1.4 Modes of Operation

There are seven modes of operation for the ICS: FEI, FEE, FBI, FBILP, FBE, FBELP, and stop.

## 11.1.4.1 FLL Engaged Internal (FEI)

In FLL engaged internal mode, which is the default mode, the ICS supplies a clock derived from the FLL which is controlled by the internal reference clock. The BDC clock is supplied from the FLL.

## 11.1.4.2 FLL Engaged External (FEE)

In FLL engaged external mode, the ICS supplies a clock derived from the FLL which is controlled by an external reference clock. The BDC clock is supplied from the FLL.

## 11.1.4.3 FLL Bypassed Internal (FBI)

In FLL bypassed internal mode, the FLL is enabled and controlled by the internal reference clock, but is bypassed. The ICS supplies a clock derived from the internal reference clock. The BDC clock is supplied from the FLL.





## 13.1.1 Features

Features of the RTC module include:

- 8-bit up-counter
  - 8-bit modulo match limit
  - Software controllable periodic interrupt on match
- Three software selectable clock sources for input to prescaler with selectable binary-based and decimal-based divider values
  - 1-kHz internal low-power oscillator (LPO)
  - External clock (ERCLK)
  - 32-kHz internal clock (IRCLK)

## 13.1.2 Modes of Operation

This section defines the operation in stop, wait and background debug modes.

## 13.1.2.1 Wait Mode

The RTC continues to run in wait mode if enabled before executing the appropriate instruction. Therefore, the RTC can bring the MCU out of wait mode if the real-time interrupt is enabled. For lowest possible current consumption, the RTC should be stopped by software if not needed as an interrupt source during wait mode.

## 13.1.2.2 Stop Modes

The RTC continues to run in stop2 or stop3 mode if the RTC is enabled before executing the STOP instruction. Therefore, the RTC can bring the MCU out of stop modes with no external components, if the real-time interrupt is enabled.

The LPO clock can be used in stop2 and stop3 modes. ERCLK and IRCLK clocks are only available in stop3 mode.

Power consumption is lower when all clock sources are disabled, but in that case, the real-time interrupt cannot wake up the MCU from stop modes.

## 13.1.2.3 Active Background Mode

The RTC suspends all counting during active background mode until the microcontroller returns to normal user operating mode. Counting resumes from the suspended value as long as the RTCMOD register is not written and the RTCPS and RTCLKS bits are not altered.





### Figure 14-5. SCI Baud Rate Register (SCIxBDL)

Table 14-2. SCIxBDL Field Descriptions

Field	Description
7:0 SBR[7:0]	<b>Baud Rate Modulo Divisor</b> — These 13 bits in SBR[12:0] are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/( $16 \times BR$ ). See also BR bits in Table 14-1.

# 14.2.2 SCI Control Register 1 (SCIxC1)

This read/write register is used to control various optional features of the SCI system.

_	7	6	5	4	3	2	1	0
R W	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
Reset	0	0	0	0	0	0	0	0

#### Figure 14-6. SCI Control Register 1 (SCIxC1)

#### Table 14-3. SCIxC1 Field Descriptions

Field	Description
7 LOOPS	<ul> <li>Loop Mode Select — Selects between loop back modes and normal 2-pin full-duplex modes. When LOOPS = 1, the transmitter output is internally connected to the receiver input.</li> <li>0 Normal operation — RxD and TxD use separate pins.</li> <li>1 Loop mode or single-wire mode where transmitter outputs are internally connected to receiver input. (See RSRC bit.) RxD pin is not used by SCI.</li> </ul>
6 SCISWAI	<ul> <li>SCI Stops in Wait Mode</li> <li>SCI clocks continue to run in wait mode so the SCI can be the source of an interrupt that wakes up the CPU.</li> <li>SCI clocks freeze while CPU is in wait mode.</li> </ul>
5 RSRC	<ul> <li>Receiver Source Select — This bit has no meaning or effect unless the LOOPS bit is set to 1. When LOOPS = 1, the receiver input is internally connected to the TxD pin and RSRC determines whether this connection is also connected to the transmitter output.</li> <li>Provided LOOPS = 1, RSRC = 0 selects internal loop back mode and the SCI does not use the RxD pins.</li> <li>Single-wire SCI mode where the TxD pin is connected to the transmitter output.</li> </ul>
4 M	<ul> <li>9-Bit or 8-Bit Mode Select</li> <li>0 Normal — start + 8 data bits (LSB first) + stop.</li> <li>1 Receiver and transmitter use 9-bit data characters start + 8 data bits (LSB first) + 9th data bit + stop.</li> </ul>



Chapter 14 Serial Communications Interface (S08SCIV4)



Field	Description
4 MSTR	Master/Slave Mode Select         0 SPI module configured as a slave SPI device         1 SPI module configured as a master SPI device
3 CPOL	<ul> <li>Clock Polarity — This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to Section 15.5.1, "SPI Clock Formats" for more details.</li> <li>0 Active-high SPI clock (idles low)</li> <li>1 Active-low SPI clock (idles high)</li> </ul>
2 CPHA	<ul> <li>Clock Phase — This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to Section 15.5.1, "SPI Clock Formats" for more details.</li> <li>0 First edge on SPSCK occurs at the middle of the first cycle of an 8-cycle data transfer</li> <li>1 First edge on SPSCK occurs at the start of the first cycle of an 8-cycle data transfer</li> </ul>
1 SSOE	<b>Slave Select Output Enable</b> — This bit is used in combination with the mode fault enable (MODFEN) bit in SPCR2 and the master/slave (MSTR) control bit to determine the function of the SS pin as shown in Table 15-2.
0 LSBFE	<ul> <li>LSB First (Shifter Direction)</li> <li>0 SPI serial data transfers start with most significant bit</li> <li>1 SPI serial data transfers start with least significant bit</li> </ul>

Table 15-2. SS Pin Function

MODFEN	SSOE	Master Mode	Slave Mode
0	0	General-purpose I/O (not SPI)	Slave select input
0	1	General-purpose I/O (not SPI)	Slave select input
1	0	SS input for mode fault	Slave select input
1	1	Automatic SS output	Slave select input

## NOTE

Ensure that the SPI should not be disabled (SPE=0) at the same time as a bit change to the CPHA bit. These changes should be performed as separate operations or unexpected behavior may occur.

# 15.4.2 SPI Control Register 2 (SPIxC2)

This read/write register is used to control optional features of the SPI system. Bits 7, 6, 5, and 2 are not implemented and always read 0.







#### Chapter 16 Timer/PWM Module (S08TPMV3)

(becomes unlatched) when the TPMxCnSC register is written (whether BDM mode is active or not). Any write to the channel registers will be ignored during the input capture mode.

When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxCnSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the channel register are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution. The value read from the TPMxCnVH and TPMxCnVL registers in BDM mode is the value of these registers and not the value of their read buffer.

In output compare or PWM modes, writing to either byte (TPMxCnVH or TPMxCnVL) latches the value into a buffer. After both bytes are written, they are transferred as a coherent 16-bit value into the timer-channel registers according to the value of CLKSB:CLKSA bits and the selected mode, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written.
- If (CLKSB:CLKSA not = 0:0 and in output compare mode) then the registers are updated after the second byte is written and on the next change of the TPM counter (end of the prescaler counting).
- If (CLKSB:CLKSA not = 0:0 and in EPWM or CPWM modes), then the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter then the update is made when the TPM counter changes from 0xFFFE to 0xFFFF.

The latching mechanism may be manually reset by writing to the TPMxCnSC register (whether BDM mode is active or not). This latching mechanism allows coherent 16-bit writes in either big-endian or little-endian order which is friendly to various compiler implementations.

When BDM is active, the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active even if one or both halves of the channel register are written while BDM is active. Any write to the channel registers bypasses the buffer latches and directly write to the channel register while BDM is active. The values written to the channel register while BDM is active are used for PWM & output compare operation once normal execution resumes. Writes to the channel registers while BDM is active do not interfere with partial completion of a coherency sequence. After the coherency mechanism has been fully exercised, the channel registers are updated using the buffered values written (while BDM was not active) by the user.

# 16.4 Functional Description

All TPM functions are associated with a central 16-bit counter which allows flexible selection of the clock source and prescale factor. There is also a 16-bit modulo register associated with the main counter.

The CPWMS control bit chooses between center-aligned PWM operation for all channels in the TPM (CPWMS=1) or general purpose timing functions (CPWMS=0) where each channel can independently be configured to operate in input capture, output compare, or edge-aligned PWM mode. The CPWMS control bit is located in the main TPM status and control register because it affects all channels within the TPM and influences the way the main counter operates. (In CPWM mode, the counter changes to an up/down mode rather than the up-counting mode used for general purpose timer functions.)



#### **Chapter 17 Development Support**

Figure 17-3 shows the host receiving a logic 1 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the perceived start of the bit time in the target MCU. The host holds the BKGD pin low long enough for the target to recognize it (at least two target BDC cycles). The host must release the low drive before the target MCU drives a brief active-high speedup pulse seven cycles after the perceived start of the bit time. The host should sample the bit level about 10 cycles after it started the bit time.



Figure 17-3. BDC Target-to-Host Serial Bit Timing (Logic 1)



Field	Description
2 WS	<ul> <li>Wait or Stop Status — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands.</li> <li>0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active)</li> <li>1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode</li> </ul>
1 WSF	<ul> <li>Wait or Stop Failure Status — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.)</li> <li>0 Memory access did not conflict with a wait or stop instruction</li> <li>1 Memory access command failed because the CPU entered wait or stop mode</li> </ul>
0 DVF	<ul> <li>Data Valid Failure Status — This status bit is not used in the MC9S08SH32 Series because it does not have any slow access memory.</li> <li>0 Memory access did not conflict with a slow memory access</li> <li>1 Memory access command failed because CPU was not finished with a slow memory access</li> </ul>

#### Table 17-2. BDCSCR Register Field Descriptions (continued)

## 17.4.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ\_BKPT and WRITE\_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 17.2.4, "BDC Hardware Breakpoint."

# 17.4.2 System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE\_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



**Appendix A Electrical Characteristics** 





